



PRODUCT DATA SHEET



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Datasheet



Resources

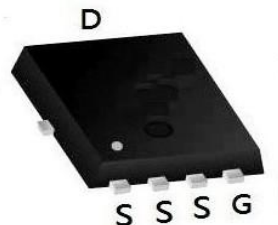
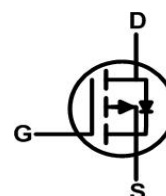


Samples

Please note: Please check the JINGAO Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.jg-semi.cn. Please email any questions regarding the system integration to JINGAO_questions@jgsemi.com.

Product Summary

BVDSS	RDSON	ID
-30V	2.5mΩ	-110A


PDFN5060-8L


- ★ Super Low Gate Charge
- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	-30	V
V_{GS}	Gate-Source Voltage	±20	V
$I_D@T_C=25^{\circ}C$	Continuous Drain Current, $V_{GS} @ -10V^{1,6}$	-110	A
$I_D@T_C=100^{\circ}C$	Continuous Drain Current, $V_{GS} @ -10V^{1,6}$	-70	A
I_{DM}	Pulsed Drain Current ²	-450	A
EAS	Single Pulse Avalanche Energy ³	576	mJ
I_{AS}	Avalanche Current	-70	A
$P_D@T_C=25^{\circ}C$	Total Power Dissipation ⁴	6.0	W
T_{STG}	Storage Temperature Range	-55 to 175	°C
T_J	Operating Junction Temperature Range	-55 to 175	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient ¹ ($t \leq 10S$)	---	20	°C/W
	Thermal Resistance Junction-ambient ¹ (Steady State)	---	50	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-case ¹	---	3.6	°C/W

Table 3. Electrical Characteristics (T_J=25°C unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =-250μA	-30			V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} =-30V, V _{GS} =0V			-1	μA
I _{GSS}	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA	-1	-1.7	-2.5	V
g _{FS}	Forward Transconductance	V _{DS} =-5V, I _D =-20A		65		S
R _{DS(ON)}	Drain-Source On-State Resistance	V _{GS} =-10V, I _D =-20A		2.5	3.1	mΩ
		V _{GS} =-4.5V, I _D =-20A		4	5.2	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =-15V, V _{GS} =0V, f=1.0MHz		7000		pF
C _{oss}	Output Capacitance			820		pF
C _{rss}	Reverse Transfer Capacitance			540		pF
R _g	Gate resistance	V _{GS} =0V, V _{DS} =0V, f=1.0MHz		2.2		Ω
Switching Parameters						
t _{d(on)}	Turn-on Delay Time	V _{GS} =-10V, V _{DS} =-15V, R _L =0.75Ω, R _{GEN} =3Ω		14		nS
t _r	Turn-on Rise Time			13		nS
t _{d(off)}	Turn-Off Delay Time			65		nS
t _f	Turn-Off Fall Time			37		nS
Q _g	Total Gate Charge	V _{GS} =-10V, V _{DS} =-15V, I _D =-20A		130		nC
Q _{gs}	Gate-Source Charge			12		nC
Q _{gd}	Gate-Drain Charge			31		nC
Source-Drain Diode Characteristics						
I _{SD}	Source-Drain Current (Body Diode)				-108	A
V _{SD}	Forward on Voltage ^(Note 3)	V _{GS} =0V, I _S =-20A			-1.2	V
t _{rr}	Reverse Recovery Time	I _F =-20A, di/dt=100A/μs		30		ns
Q _{rr}	Reverse Recovery Charge	I _F =-20A, di/dt=100A/μs		40		nC

Notes 1.Repetitive Rating: Pulse width limited by maximum junction temperature.

Notes 2.E_{AS} condition: T_J=25°C, V_{DD}=15V, V_G=-10V, R_g=25Ω, L=0.5mH.

Notes 3.Repetitive Rating: Pulse width limited by maximum junction temperature.

Typical Electrical And Thermal Characteristics (Curves)

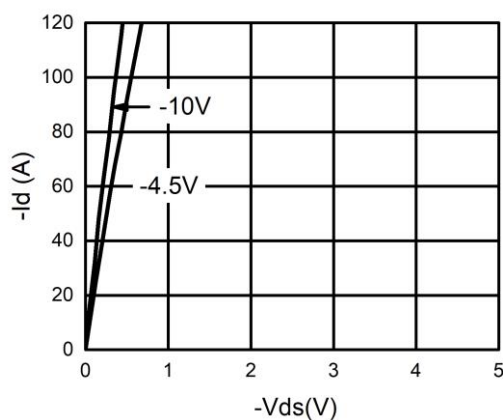
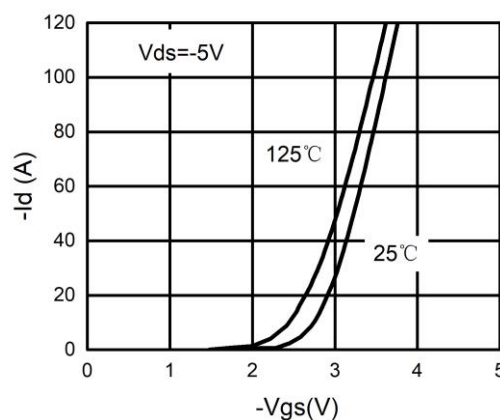
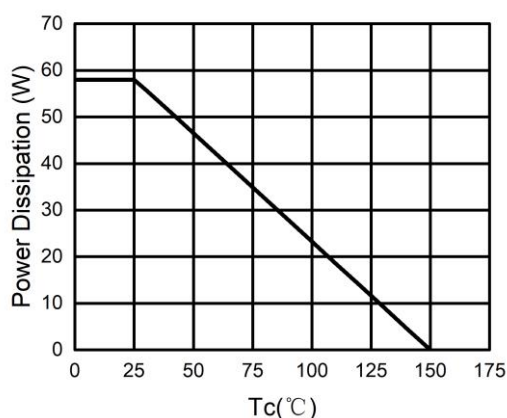
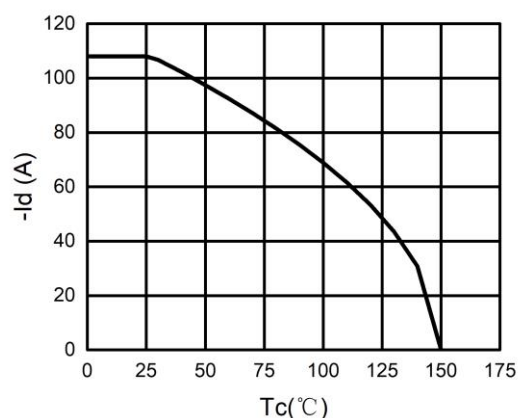
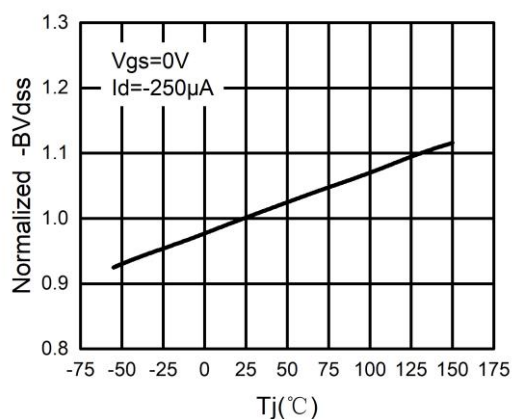
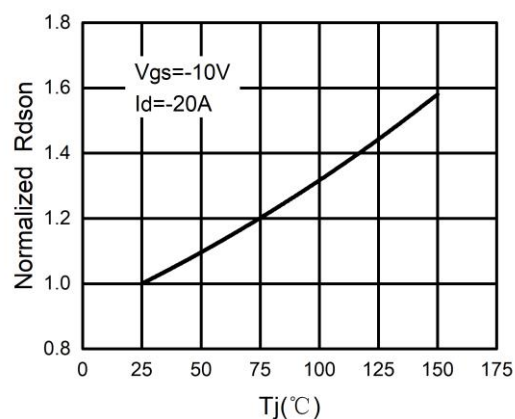
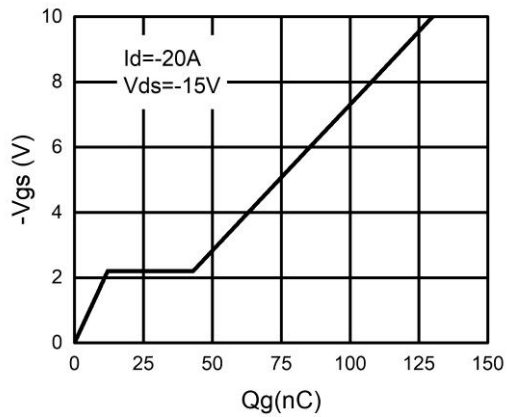
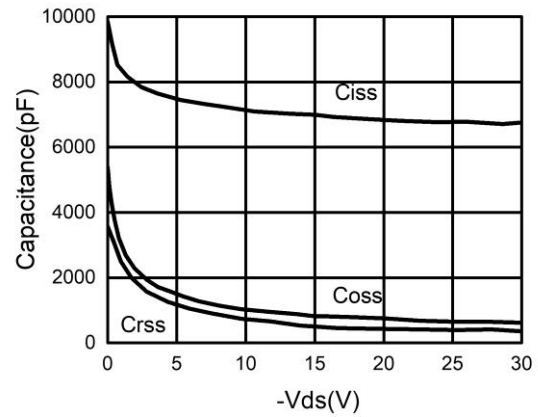
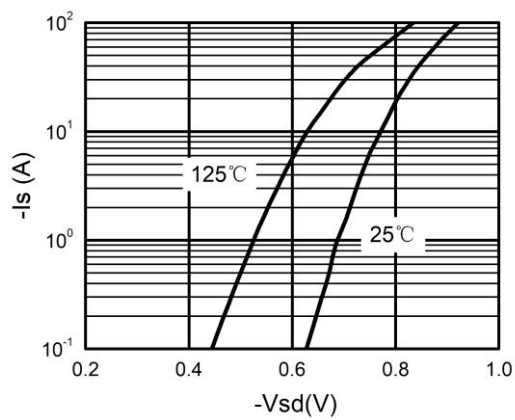
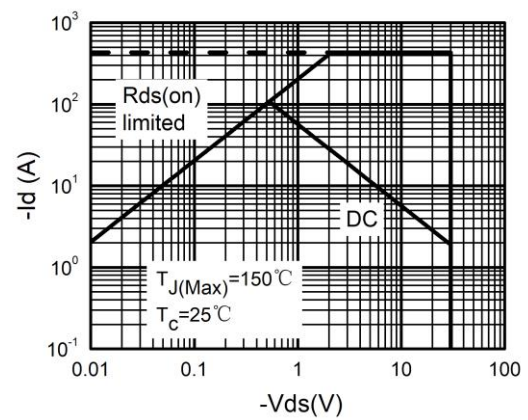
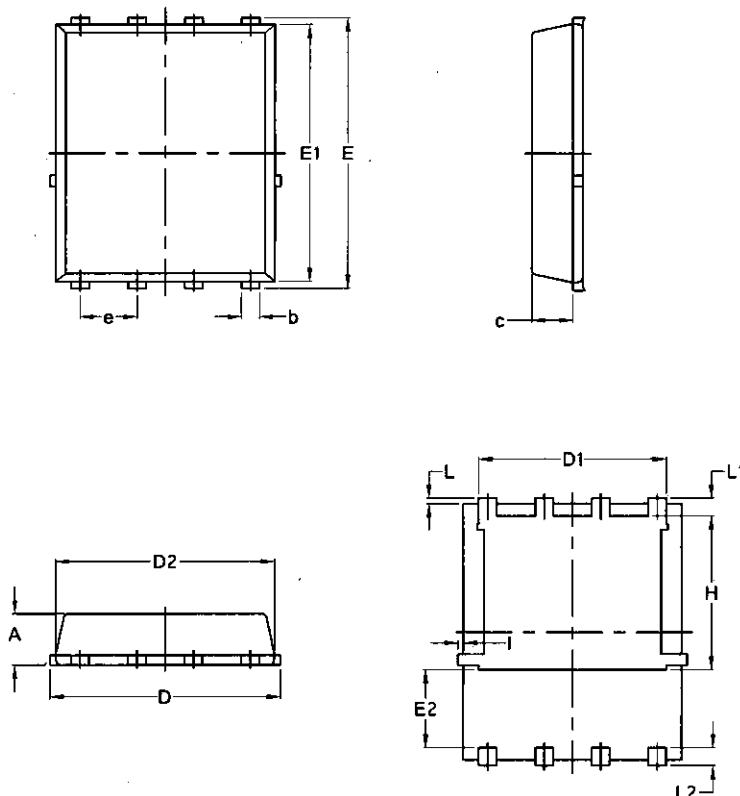
Figure 1. Output Characteristics

Figure 2. Transfer Characteristics

Figure 3. Power Dissipation

Figure 4. Drain Current

Figure 5. BV_{DSS} vs Junction Temperature

Figure 6. $R_{DS(ON)}$ vs Junction Temperature


Figure 7. Gate Charge Waveforms

Figure 8. Capacitance

Figure 9. Body-Diode Characteristics

Figure 10. Maximum Safe Operating Area


Package Mechanical Data-PDFN5060-8L-Single



Symbol	Common			
	mm		Inch	
	Min	Max	Min	Max
A	1.03	1.17	0.0406	0.0461
b	0.34	0.48	0.0134	0.0189
c	0.824	0.0970	0.0324	0.082
D	4.80	5.40	0.1890	0.2126
D1	4.11	4.31	0.1618	0.1697
D2	4.80	5.00	0.1890	0.1969
E	5.95	6.15	0.2343	0.2421
E1	5.65	5.85	0.2224	0.2303
E2	1.60	/	0.0630	/
e	1.27 BSC		0.05 BSC	
L	0.05	0.25	0.0020	0.0098
L1	0.38	0.50	0.0150	0.0197
L2	0.38	0.50	0.0150	0.0197
H	3.30	3.50	0.1299	0.1378
I	/	0.18	/	0.0070

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